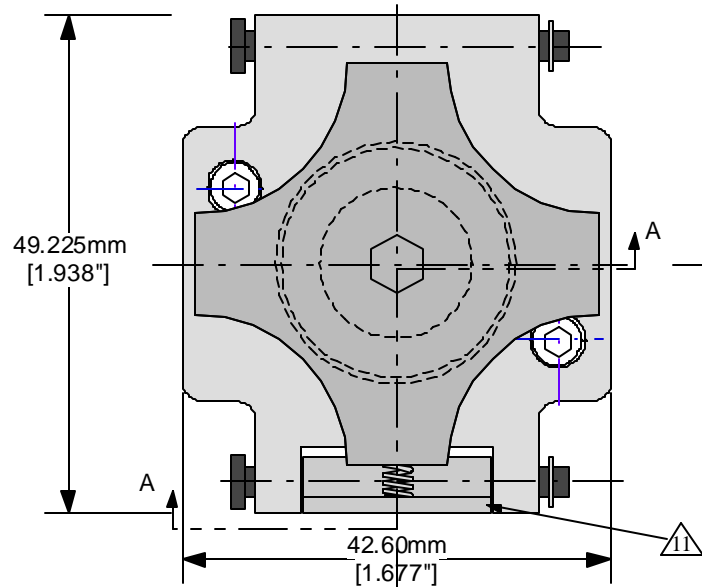
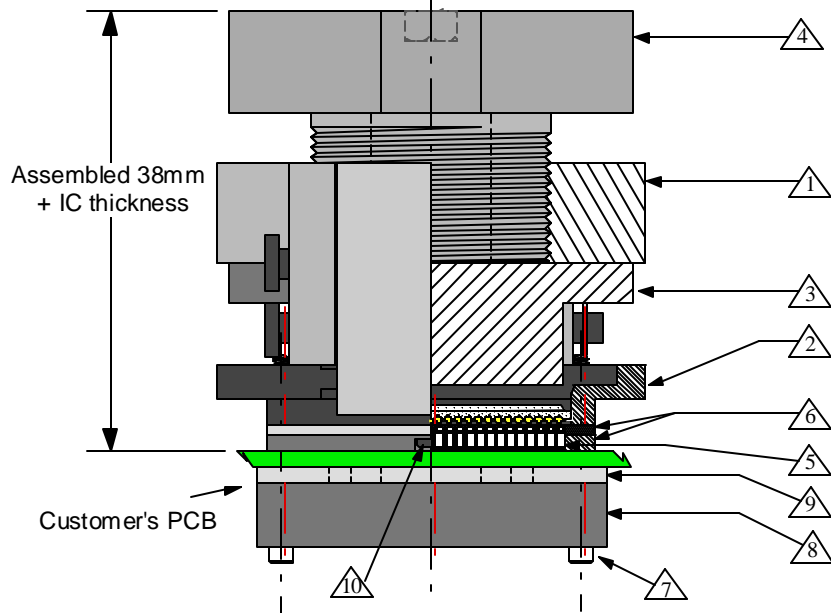


Top View



Side View  
(Section AA)




**Features**

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

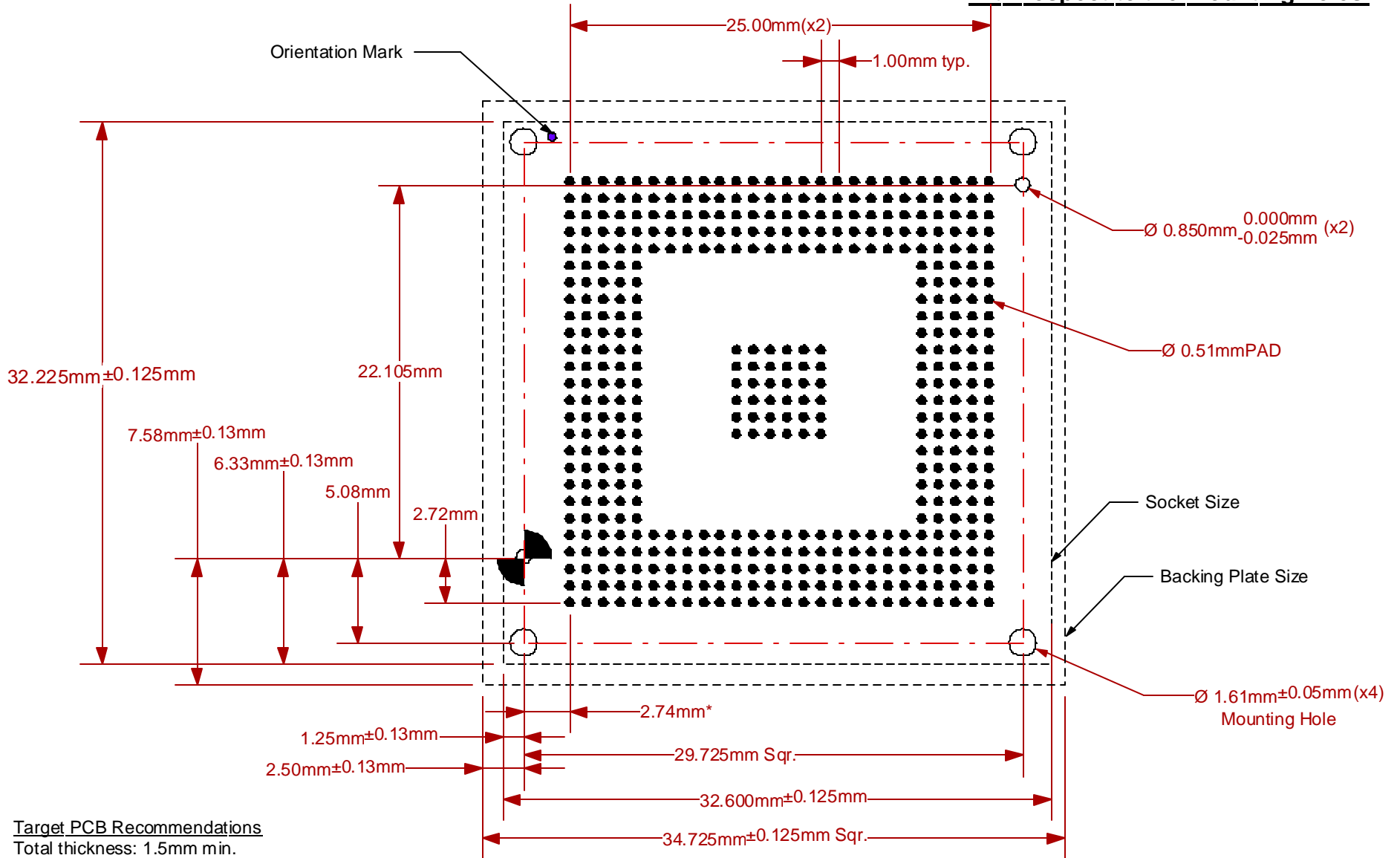
Materials:

- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- 5 Pogo Pin:  
Plungers - Hardened Steel/ Gold plated  
Barrel - Copper Alloy/ Gold plated  
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ultem 1000.
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 3/4" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8 SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized 7075 Aluminum.

All Tolerances:  $\pm 0.125\text{mm}$  (unless stated otherwise). Materials and specifications are subject to change without notice.


	<b>SS-BGA456D-01 Drawing</b>	Status: Released	Scale: 1.25:1	Rev: B
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 5/7/04	
		File: SS-BGA456D-01 Dwg	Modified: 1/21/05	

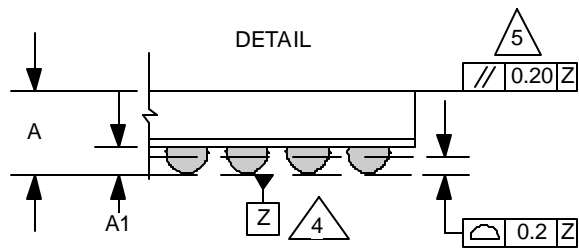
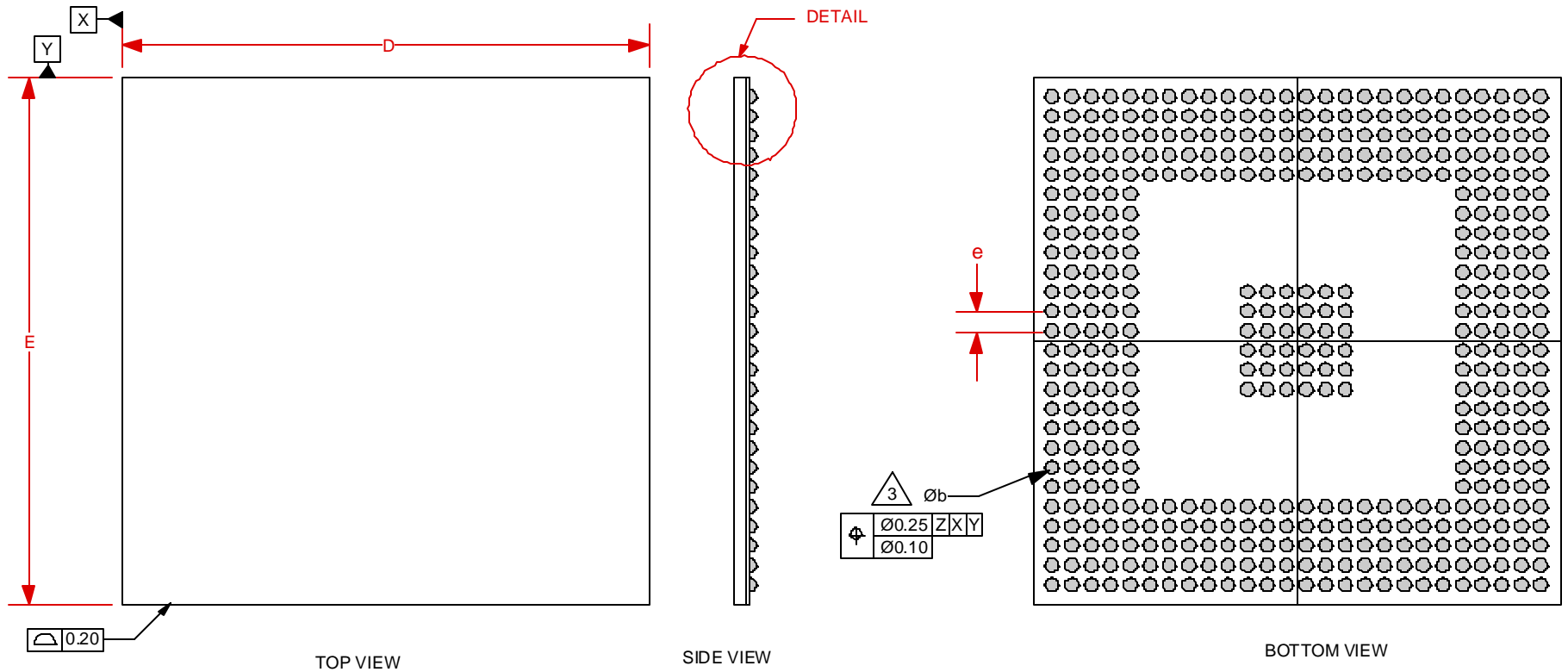
**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**



**Target PCB Recommendations**  
Total thickness: 1.5mm min.  
Plating: Gold or Solder finish

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	<b>SS-BGA456D-01 Drawing</b>	Status: Released	Scale: 3:1	Rev: B
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 5/7/04
		File: SS-BGA456D-01 Dwg		Modified: 1/21/05



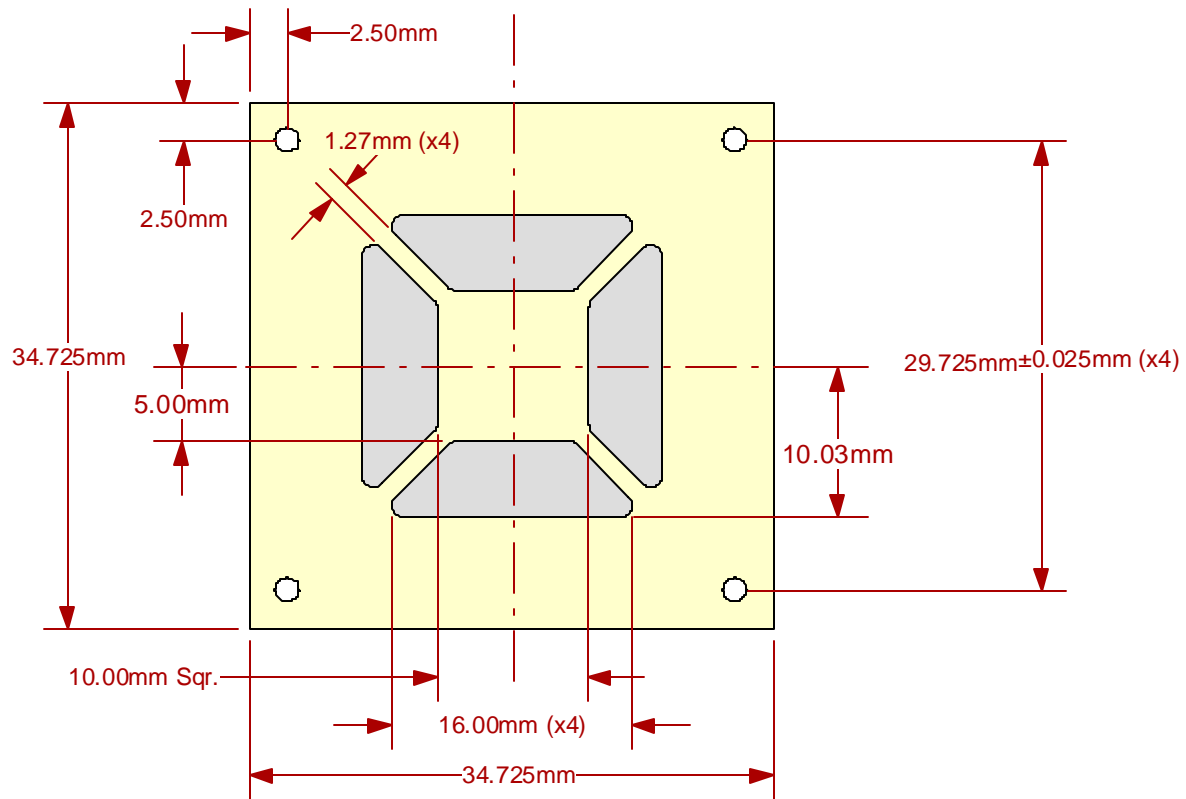
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.5
A1	0.4	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

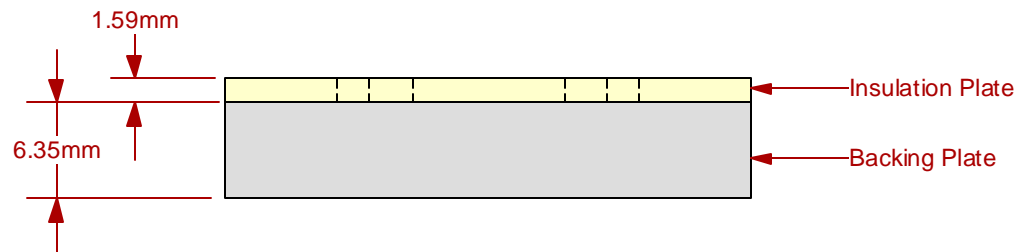
26x26 Array

	<b>SS-BGA456D-01 Drawing</b>		Status: Released	Scale:	Rev: B	
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com			Drawing: H. Hansen		Date: 5/7/04
				File: SS-BGA456D-01 Dwg	Modified: 1/21/05	


Top View



Side View



Description: Backing Plate with Insulation Plate

	<b>SS-BGA456D-01 Drawing</b>	Status: Released	Scale:	Rev: B
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 5/7/04
		File: SS-BGA456D-01 Dwg	Modified: 1/21/05	

All dimensions are in mm.  
All tolerances are +/- 0.125mm.  
(Unless stated otherwise)